

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ference et al.

Confirmation No.:

Serial No.:

Group Art Unit:

Filed: Herewith

Examiner:

Title: **MULTI-CHIP STACK AND METHOD OF FABRICATION UTILIZING
SELF ALIGNING ELECTRICAL CONTRACT ARRAY**

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**STATEMENT OF RELEVANCE FOR INFORMATION
DISCLOSED BY APPLICANT**

Sir:

The following Statement of Relevance is submitted with the accompanying Information Disclosure Citation form.

Document <u>Designation</u>	<u>Relevance</u>
05-190553	Mounting structure of semiconductor component and manufacture of its solder bump
JP4088645	Conductive paste and mounting of semiconductor device

Full text copies of the art cited, or the pertinent portions thereof, are enclosed. It is respectfully requested that this art be considered by the Examiner in the above-entitled application and made of record therein. The information provided and references enclosed herewith shall not be construed as a representation that a search has been made or that no other art than that identified exists.

Respectfully submitted,

December 04, 2003
Date


Kevin P. Radigan
Attorney for Applicants
Registration No.: 35,670

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application: Ference et al.

Group Art Unit: : IBM Corporation
Examiner: : Intellectual Property Law
Serial No.: : Mail 972E
Filed: Herewith : 1000 River Street
Title: MULTI-CHIP STACK AND METHOD : Essex Junction, VT 05432
OF FABRICATION UTILIZING SELF-
ALIGNING ELECTRICAL CONTACT
ARRAY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INFORMATION DISCLOSURE STATEMENT

It is respectfully requested that the publications identified below and listed on the enclosed PTO 1449 Form(s) be considered by the United States Patent and Trademark Office (USPTO) in the subject United States patent application and be made of record therein. A copy of each publication is enclosed, and this submission is otherwise believed to be in compliance with 37 C.F.R. Sections 1.97 and 1.98. This information is all the material information, as defined in 37 C.F.R. Section 1.56(a), of which the submitter is aware. However, no representation is made or intended that a search has been made or that no other such material information exists.

PATENTS

- | | | | |
|---------------|---------------|---------------|---------------|
| 1. 3,869,787 | 2. 4,032,058 | 3. 4,182,781 | 4. 4,487,654 |
| 5. 5,226,232 | 6. 5,381,307 | 7. 5,497,258 | 8. 5,567,295 |
| 9. 5,567,654 | 10. 5,646,828 | 11. 5,796,591 | 12. 5,863,406 |
| 13. 6,133,637 | 14. 6,137,184 | 15. 6,166,556 | 16. 6,268,739 |
| 17. 6,337,522 | 18. 05-190553 | 19. JP4088645 | |

None of the above cited publications, taken singularly or in combination, is believed to teach or suggest the invention as defined by the claims provided in the instant application.

Respectfully submitted,

Dated: December 4, 2003
Telephone No.: (518) 452-5600
Fax No.: (518) 452-5579

By: Kevin P. Radigan
Kevin P. Radigan
Reg. No. 31,789

INFORMATION DISCLOSURE CITATION
(USE SEVERAL SHEETS IF NECESSARY)

 ATTY DOCKET NO.
 BUR919990304US2

SERIAL NO.

 APPLICANT(S)
FERENCE ET AL.

 FILING DATE
 HEREWITH

GROUP

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	3,869,787	03/11/75	Umbaugh	29	577	
	AB	4,032,058	06/28/77	Riseman	228	180	
	AC	4,182,781	01/08/80	Hooper et al.	427	90	
	AD	4,487,654	12/11/84	Coppin	156	645	
	AE	5,226,232	07/13/93	Boyd	29	846	
	AF	5,381,307	01/10/95	Hertz et al.	361	767	
	AG	5,497,258	03/05/96	Ju et al.	359	83	
	AH	5,567,295	10/22/96	Swamy et al.	205	125	
	AI	5,567,654	10/22/96	Beilstein, Jr. et al.	437	209	
	AJ	5,646,828	07/08/97	Degani et al.	361	715	
	AK	5,796,591	08/18/98	Dalal et al.	361	779	
	AL	5,863,406	01/26/99	Mazzoni et al.	205	126	
	AM	6,133,637	10/17/00	Hikita et al.	257	777	
	AN	6,137,184	10/24/00	Ikegami	257	785	
	AO	6,166,556	12/26/00	Wang et al.	324	765	
	AP	6,268,739 B1	07/31/01	Bernier et al.	324	755	
	AQ	6,337,522 B1	01/08/02	Kang et al.	257	784	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION		
							NO	YES	ABSTRACT
	AR	05-190553	07/30/93	Japan	H01L	21/321	X		X
	AS	JP4088645	03/23/92	Japan	H01L	21/60	X		X

EXAMINER
DATE CONSIDERED

EXAMINER: Initial here if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION <i>(USE SEVERAL SHEETS IF NECESSARY)</i>	ATTY DOCKET NO.	SERIAL NO.
	BUR919990304US2	
	APPLICANT(S) FERENCE ET AL.	
FILING DATE HEREWITH	GROUP	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER _____ **DATE CONSIDERED** _____

EXAMINER: Initial here if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. **Include copy of this form with next communication to applicant.**